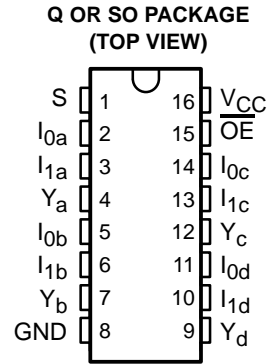


# CY74FCT257T QUAD 2-INPUT MULTIPLEXER WITH 3-STATE OUTPUTS

SCCS019D – MAY 1994 – REVISED NOVEMBER 2001

- **Function, Pinout, and Drive Compatible With FCT and F Logic**
- **Reduced  $V_{OH}$  (Typically = 3.3 V) Version of Equivalent FCT Functions**
- **Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics**
- **$I_{off}$  Supports Partial-Power-Down Mode Operation**
- **Matched Rise and Fall Times**
- **Fully Compatible With TTL Input and Output Logic Levels**
- **ESD Protection Exceeds JESD 22**
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- **64-mA Output Sink Current**  
**32-mA Output Source Current**
- **3-State Outputs**



## description

The CY74FCT257T has four identical two-input multiplexers that select four bits of data from two sources under the control of a common data-select (S) input. The  $I_0$  inputs are selected when S is low, and the  $I_1$  inputs are selected when S is high. Data at the output is noninverted.

The CY74FCT257T is a logic implementation of a four-pole, two-position switch, where the position of the switch is determined by the logic levels at S. Outputs are in the high-impedance state when the output-enable ( $\overline{OE}$ ) input is high.

All but one device must be in the high-impedance state to avoid currents exceeding the maximum ratings if outputs are tied together.  $\overline{OE}$  inputs must ensure that there is no overlap when outputs of 3-state devices are tied together.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### PIN DESCRIPTION

NAME	DESCRIPTION
I	Data inputs
S	Common data-select input
$\overline{OE}$	Output-enable input (active low)
Y	Data outputs



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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# CY74FCT257T QUAD 2-INPUT MULTIPLEXER WITH 3-STATE OUTPUTS

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## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	4.3	CY74FCT257CTQCT	FT257-3
	SOIC – SO	Tube	4.3	CY74FCT257CTSOC	FCT257C
		Tape and reel	4.3	CY74FCT257CTSOCT	
	QSOP – Q	Tape and reel	5	CY74FCT257ATQCT	FT257-1
	QSOP – Q	Tape and reel	6	CY74FCT257TQCT	FT257

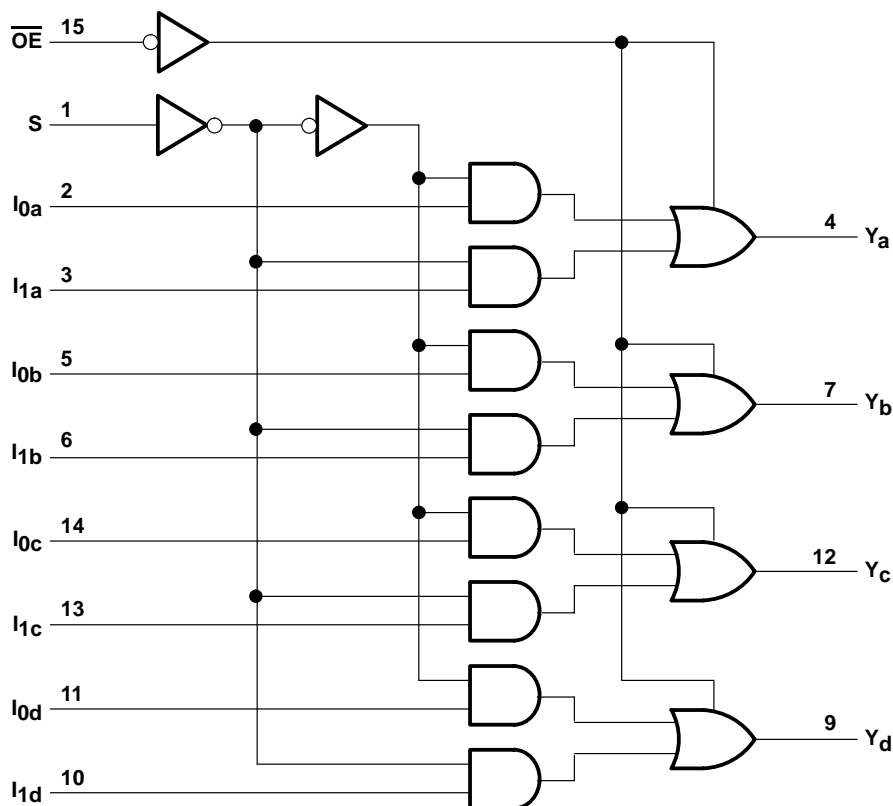
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE

INPUTS				OUTPUT
$\overline{OE}$	S	I <sub>0</sub>	I <sub>1</sub>	Y
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = High logic level, L = Low logic level,  
X = Don't care, Z = High-impedance state

## logic diagram



**CY74FCT257T**  
**QUAD 2-INPUT MULTIPLEXER**  
**WITH 3-STATE OUTPUTS**

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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range to ground potential .....	–0.5 V to 7 V
DC input voltage range .....	–0.5 V to 7 V
DC output voltage range .....	–0.5 V to 7 V
DC output current (maximum sink current/pin) .....	120 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): Q package .....	90°C/W
SO package .....	57°C/W
Ambient temperature range with power applied, $T_A$ .....	–65°C to 135°C
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions (see Note 2)**

	MIN	NOM	MAX	UNIT
$V_{CC}$ Supply voltage	4.75	5	5.25	V
$V_{IH}$ High-level input voltage	2			V
$V_{IL}$ Low-level input voltage			0.8	V
$I_{OH}$ High-level output current			–32	mA
$I_{OL}$ Low-level output current			64	mA
$T_A$ Operating free-air temperature	–40		85	°C

NOTE 2: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.



# CY74FCT257T

## QUAD 2-INPUT MULTIPLEXER

### WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.75$ ,	$I_{IN} = -18$ mA		-0.7	-1.2	V
$V_{OH}$	$V_{CC} = 4.75$ ,	$I_{OH} = -32$ mA	2			V
$V_{OL}$	$V_{CC} = 4.75$ ,	$I_{OL} = 64$ mA		0.3	0.55	V
$V_{hys}$	All inputs			0.2		V
$I_I$	$V_{CC} = 5.25$ V,	$V_{IN} = 5.25$ V			5	μA
$I_{IH}$	$V_{CC} = 5.25$ V,	$V_{IN} = 2.7$ V			±1	μA
$I_{IL}$	$V_{CC} = 5.25$ V,	$V_{IN} = 0.5$ V			±1	μA
$I_{OZH}$	$V_{CC} = 5.25$ V,	$V_{OUT} = 2.7$ V			10	μA
$I_{OZL}$	$V_{CC} = 5.25$ V,	$V_{OUT} = 0.5$ V			-10	μA
$I_{OS}^{\ddagger}$	$V_{CC} = 5.25$ V,	$V_{OUT} = 0$ V	-60	-120	-225	mA
$I_{off}$	$V_{CC} = 0$ V,	$V_{OUT} = 4.5$ V			±1	μA
$I_{CC}$	$V_{CC} = 5.25$ V,	$V_{IN} \leq 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V		0.1	0.2	mA
$\Delta I_{CC}$	$V_{CC} = 5.25$ V, $V_{IN} = 3.4$ V $\S$ , $f_1 = 0$ , Outputs open			0.5	2	mA
$I_{CCD}^{\parallel}$	$V_{CC} = 5.25$ V, One input switching at 50% duty cycle, Outputs open, $\overline{OE} = GND$ , $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V			0.06	0.12	mA/MHz
$I_C^{\#}$	$V_{CC} = 5.25$ V, Outputs open, $\overline{OE} = GND$	One input switching at $f_1 = 10$ MHz at 50% duty cycle	$V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V	0.7	1.4	mA
			$V_{IN} = 3.4$ V or GND	1	2.4	
		Four bits switching at $f_1 = 2.5$ MHz at 50% duty cycle	$V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V	0.7	1.4	
			$V_{IN} = 3.4$ V or GND	1.7	5.4	
$C_i$				5	10	pF
$C_o$				9	12	pF

† Typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$ .

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

§ Per TTL-driven input ( $V_{IN} = 3.4$  V); all other inputs at  $V_{CC}$  or GND

¶ This parameter is derived for use in total power-supply calculations.

#  $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD}(f_0/2 + f_1 \times N_1)$

Where:

$I_C$  = Total supply current

$I_{CC}$  = Power-supply current with CMOS input levels

$\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4$  V)

$D_H$  = Duty cycle for TTL inputs high

$N_T$  = Number of TTL inputs at  $D_H$

$I_{CCD}$  = Dynamic current caused by an input transition pair (HLH or LHL)

$f_0$  = Clock frequency for registered devices, otherwise zero

$f_1$  = Input signal frequency

$N_1$  = Number of inputs changing at  $f_1$

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the  $I_C$  formula.



**CY74FCT257T**  
**QUAD 2-INPUT MULTIPLEXER**  
**WITH 3-STATE OUTPUTS**

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switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT257T		CY74FCT257AT		CY74FCT257CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	I	Y	1.5	6	1.5	5	1.5	4.3	ns
t <sub>PHL</sub>			1.5	6	1.5	5	1.5	4.3	
t <sub>PLH</sub>	S	Y	1.5	10.5	1.5	7	1.5	5.2	ns
t <sub>PHL</sub>			1.5	10.5	1.5	7	1.5	5.2	
t <sub>PZH</sub>	$\overline{OE}$	Y	1.5	8.5	1.5	7	1.5	6	ns
t <sub>PZL</sub>			1.5	8.5	1.5	7	1.5	6	
t <sub>PHZ</sub>	$\overline{OE}$	Y	1.5	6	1.5	5.5	1.5	5	ns
t <sub>PLZ</sub>			1.5	6	1.5	5.5	1.5	5	



**CY74FCT257T**  
**QUAD 2-INPUT MULTIPLEXER**  
**WITH 3-STATE OUTPUTS**

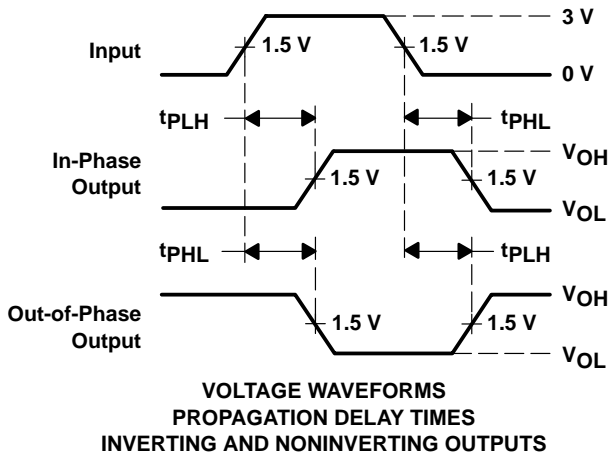
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**PARAMETER MEASUREMENT INFORMATION**



**LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS**

**LOAD CIRCUIT FOR 3-STATE OUTPUTS**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CY74FCT257ATD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257ATDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257ATDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257ATDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257ATDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257ATDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257ATQCT	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257ATQCTE4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257ATQCTG4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257CTD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTQCT	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257CTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257CTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257CTSOC	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTSOCE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTSOCG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTSUCT	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTSUCTE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257CTSUCTG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT257TQCT	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR



Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CY74FCT257TQCTE4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT257TQCTG4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT257ATDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CY74FCT257CTDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CY74FCT257CTSOCT	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT257ATDR	SOIC	D	16	2500	333.2	345.9	28.6
CY74FCT257CTDR	SOIC	D	16	2500	333.2	345.9	28.6
CY74FCT257CTSOCT	SOIC	DW	16	2000	346.0	346.0	33.0

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)

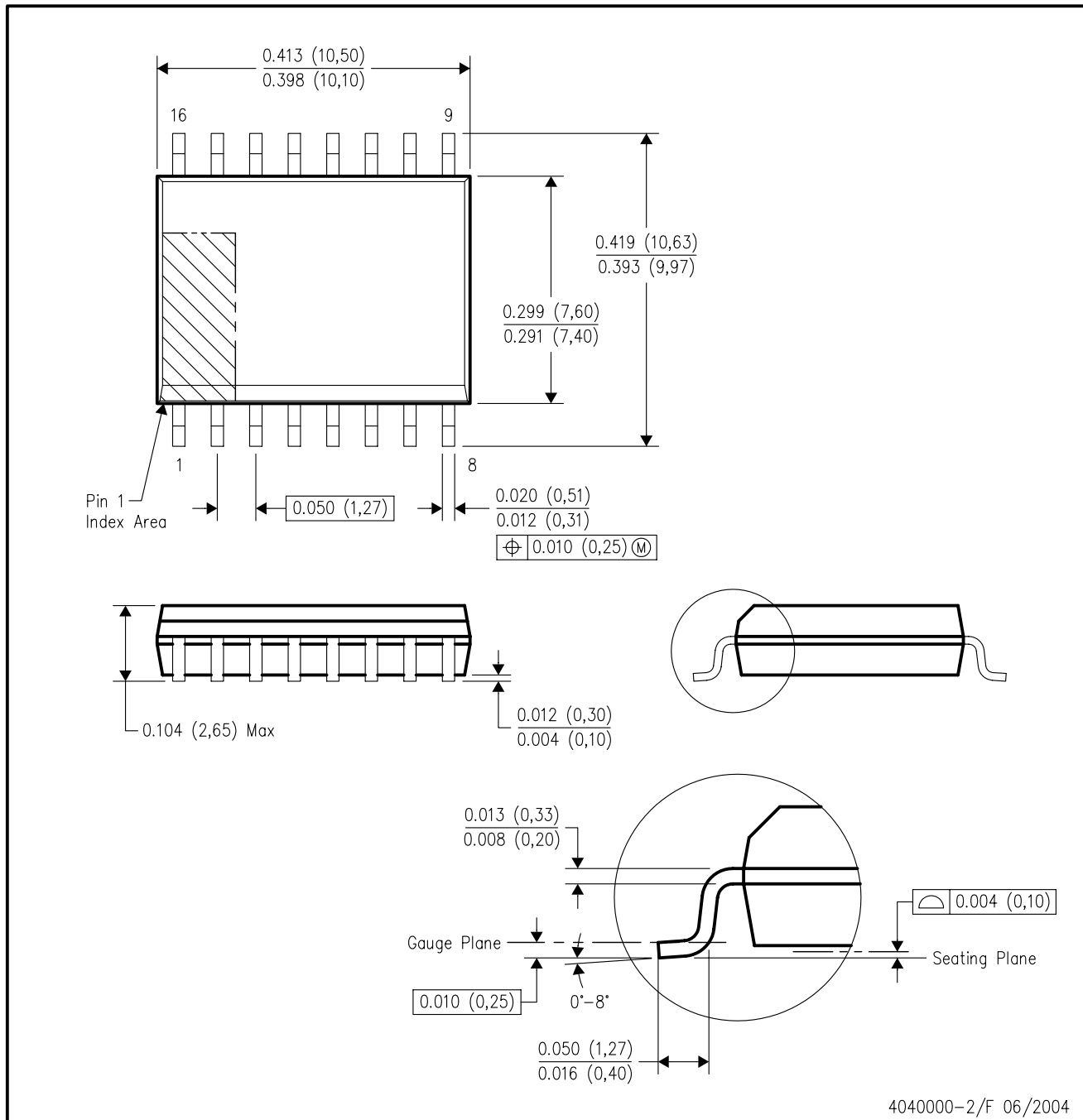


4209373/A 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE

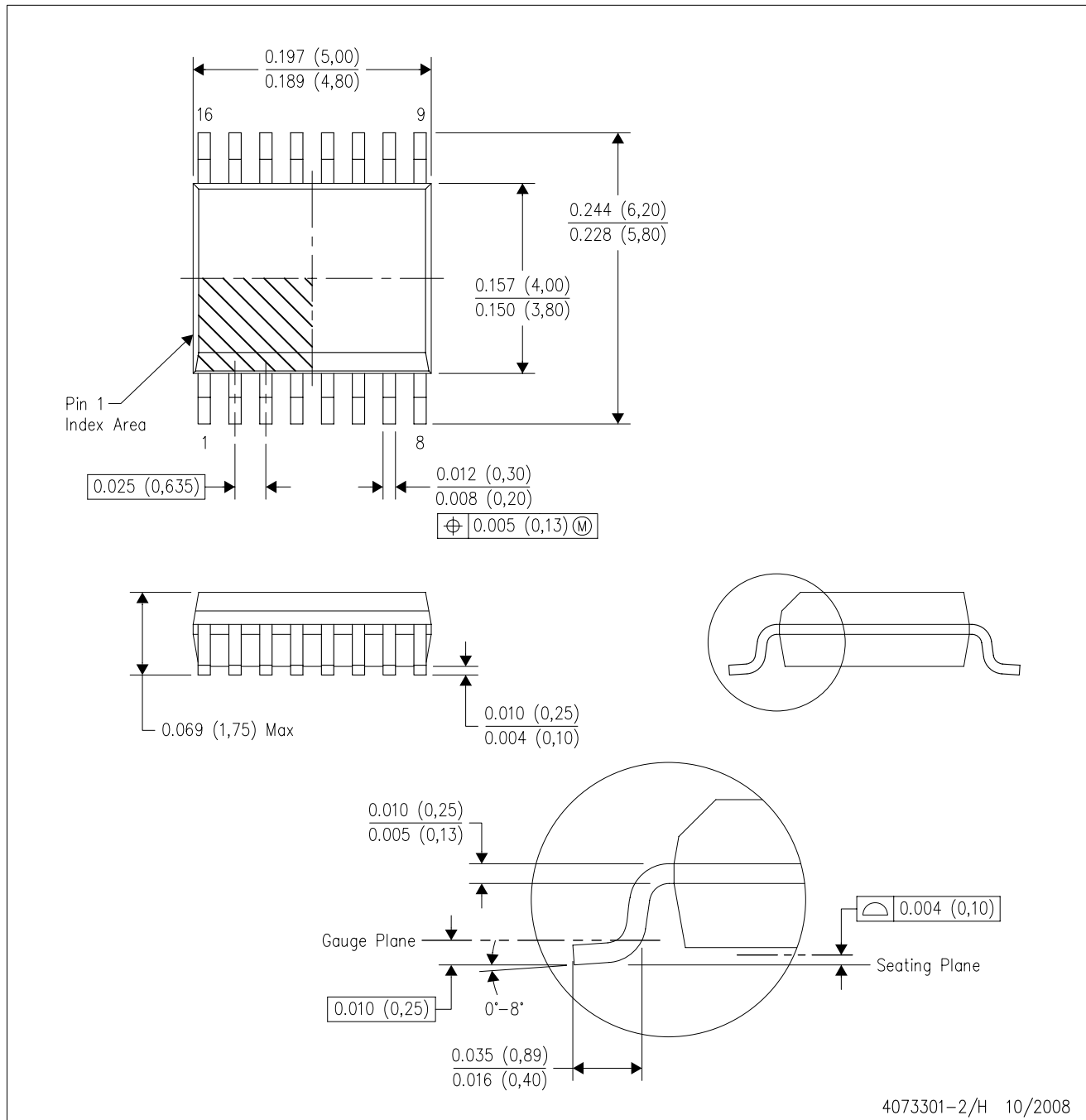


4040000-2/F 06/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AA.

DBQ (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AB.

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